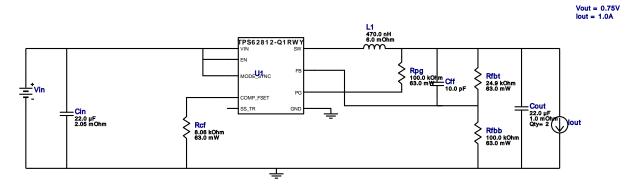
VinMin = 2.75V VinMax = 6.0V Vout = 0.75V lout = 1.0A

Device = TPS62812QWRWYRQ1 Topology = Buck Created = 2023-02-17 02:34:26.355 BOM Cost = \$1.92 BOM Count = 10 Total Pd = 0.17W

WEBENCH® Design Report

Design: 168 TPS62812QWRWYRQ1 TPS62812QWRWYRQ1 2.75V-6V to 1.80V @ 2A



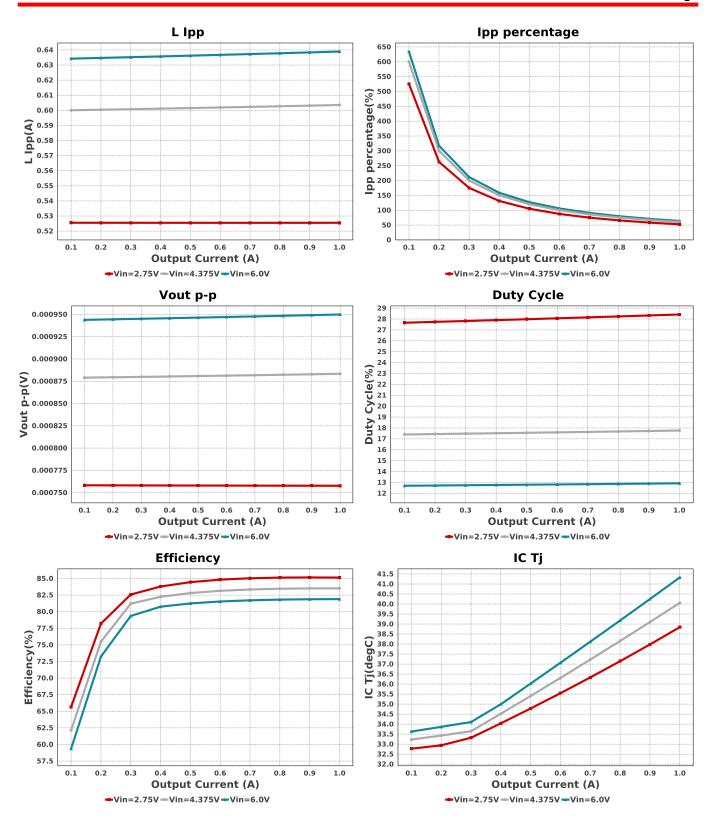
Design Alerts

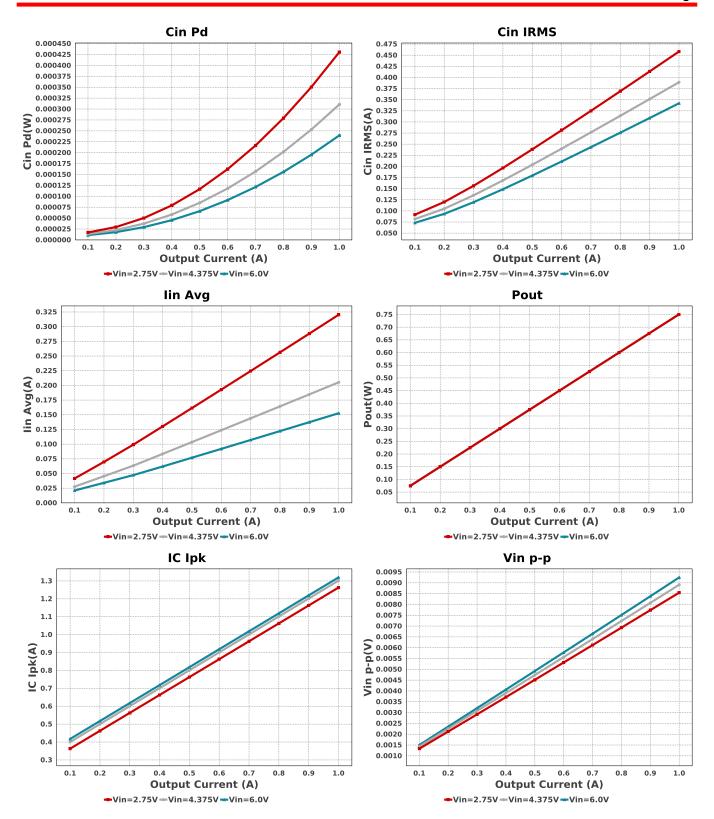
Component Selection Information

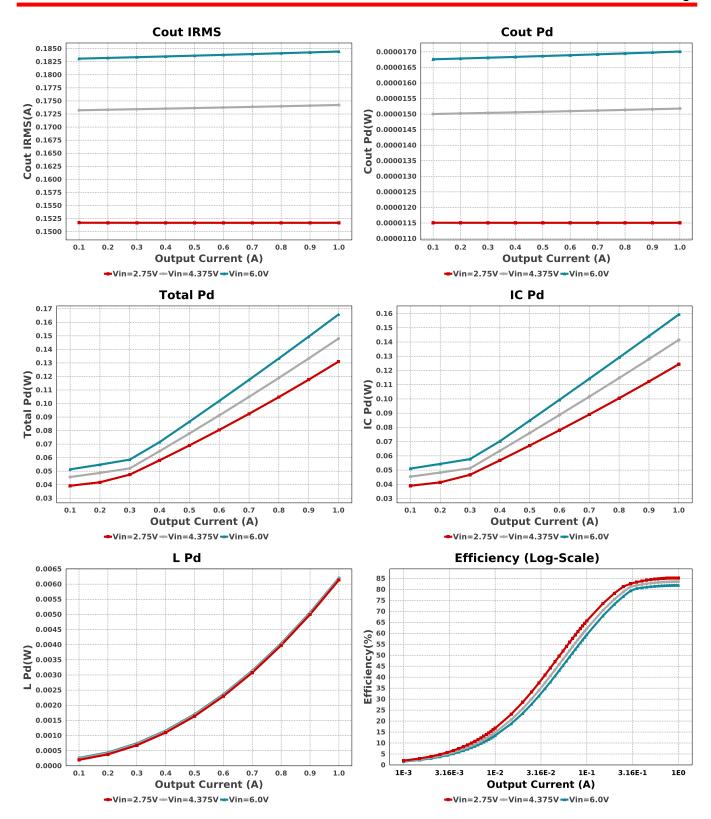
The TPS62812-Q1 is qualified for Automotive applications. All passives and other components selected in this design may not be qualified for Automotive applications. The user is required to verify that all components in the design meet the qualification and safety requirements for their specific application.

Electrical BOM

Name	Manufacturer	Part Number	Properties	Qty	Price	Footprint
Cff	Kemet	C0603C100K3GACTU Series= C0G/NP0	Cap= 10.0 pF VDC= 25.0 V IRMS= 0.0 A	1	\$0.02	0603 5 mm ²
Cin	TDK	C2012X5R1V226M125AC Series= X5R	Cap= 22.0 uF ESR= 2.05 mOhm VDC= 35.0 V IRMS= 4.5559 A	1	\$0.31	0805 7 mm ²
Cout	MuRata	GRM188R60J226MEA0D Series= X5R	Cap= 22.0 uF ESR= 1.0 mOhm VDC= 6.3 V IRMS= 6.0 A	2	\$0.04	0603 5 mm ²
L1	Vishay-Dale	IHLP2020CZERR47M11	L= 470.0 nH 6.0 mOhm	1	\$0.63	IHLP-2020CZ 54 mm ²
Rcf	Vishay-Dale	CRCW04028K06FKED Series= CRCWe3	Res= 8.06 kOhm Power= 63.0 mW Tolerance= 1.0%	1	\$0.01	0402 3 mm ²
Rfbb	Vishay-Dale	CRCW0402100KFKED Series= CRCWe3	Res= 100.0 kOhm Power= 63.0 mW Tolerance= 1.0%	1	\$0.01	0402 3 mm ²
Rfbt	Vishay-Dale	CRCW040224K9FKED Series= CRCWe3	Res= 24.9 kOhm Power= 63.0 mW Tolerance= 1.0%	1	\$0.01	0402 3 mm ²
Rpg	Vishay-Dale	CRCW0402100KFKED Series= CRCWe3	Res= 100.0 kOhm Power= 63.0 mW Tolerance= 1.0%	1	\$0.01	0402 3 mm ²
U1	Texas Instruments	TPS62812QWRWYRQ1	Switcher	1	\$0.84	RWY0009A 12 mm²







Operating Values

#	Name	Value	Category	Description
1.	Cin IRMS	341.871 mA	Capacitor	Input capacitor RMS ripple current
2.	Cin Pd	239.6 μW	Capacitor	Input capacitor power dissipation
3.	Cout IRMS	184.445 mA	Capacitor	Output capacitor RMS ripple current
4.	Cout Pd	17.01 μW	Capacitor	Output capacitor power dissipation
5.	IC lpk	1.319 A	IC	Peak switch current in IC
6.	IC Pd	159.33 mW	IC	IC power dissipation
7.	IC Tj	41.328 degC	IC	IC junction temperature
8.	IC Tolerance	6.0 mV	IC	IC Feedback Tolerance
9.	ICThetaJA	71.1 degC/W	IC	IC junction-to-ambient thermal resistance
10.	lin Avg	152.63 mA	IC	Average input current

#	Name	Value	Category	Description
11.	lpp percentage	63.894 %	Inductor	Inductor ripple current percentage (with respect to average inductor current)
12.	L lpp	638.94 mA	Inductor	Peak-to-peak inductor ripple current
13.	L Pd	6.204 mW	Inductor	Inductor power dissipation
14.	Cin Pd	239.6 μW	Power	Input capacitor power dissipation
15.	Cout Pd	17.01 µW	Power	Output capacitor power dissipation
16.	IC Pd	159.33 mW	Power	IC power dissipation
17.	L Pd	6.204 mW	Power	Inductor power dissipation
18.	Total Pd	165.793 mW	Power	Total Power Dissipation
19.	BOM Count	10	System Information	Total Design BOM count
20.	Duty Cycle	12.917 %	System Information	Duty cycle
21.	Efficiency	81.896 %	System Information	Steady state efficiency
22.	FootPrint	99.0 mm²	System Information	Total Foot Print Area of BOM components
23.	Frequency	2.233 MHz	System Information	Switching frequency
24.	lout	1.0 A	System Information	lout operating point
25.	Mode	FCCM	System Information	Conduction Mode
26.	Pout	750.0 mW	System Information	Total output power
27.	Total BOM	\$1.92	System Information	Total BOM Cost
28.	Vin	6.0 V	System Information	Vin operating point
29.	Vin p-p	9.249 mV	System Information	Peak-to-peak input voltage
30.	Vout	750.0 mV	System Information	Operational Output Voltage
31.	Vout Actual	749.4 mV	System Information	Vout Actual calculated based on selected voltage divider resistors
32.	Vout Tolerance	1.407 %	System Information	Vout Tolerance based on IC Tolerance (no load) and voltage divider resistors if applicable
33.	Vout p-p	949.917 μV	System Information	Peak-to-peak output ripple voltage

Design Inputs

Name	Value	Description	
lout	1.0	Maximum Output Current	
VinMax	6.0	Maximum input voltage	
VinMin	2.75	Minimum input voltage	
Vout	750.0 m	Output Voltage	
base_pn	TPS62812-Q1	Base Product Number	
source	DC	Input Source Type	
Та	30.0	Ambient temperature	

WEBENCH® Assembly

Component Testing

Some published data on components in datasheets such as Capacitor ESR and Inductor DC resistance is based on conservative values that will guarantee that the components always exceed the specification. For design purposes it is usually better to work with typical values. Since this data is not always available it is a good practice to measure the Capacitance and ESR values of Cin and Cout, and the inductance and DC resistance of L1 before assembly of the board. Any large discrepancies in values should be electrically simulated in WEBENCH to check for instabilities and thermally simulated in WebTHERM to make sure critical temperatures are not exceeded.

Soldering Component to Board

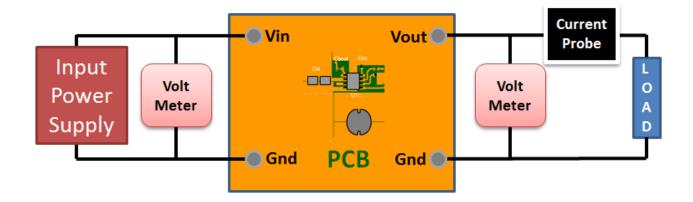
If board assembly is done in house it is best to tack down one terminal of a component on the board then solder the other terminal. For surface mount parts with large tabs, such as the DPAK, the tab on the back of the package should be pre-tinned with solder, then tacked into place by one of the pins. To solder the tab town to the board place the iron down on the board while resting against the tab, heating both surfaces simultaneously. Apply light pressure to the top of the plastic case until the solder flows around the part and the part is flush with the PCB. If the solder is not flowing around the board you may need a higher wattage iron (generally 25W to 30W is enough).

Initial Startup of Circuit

It is best to initially power up the board by setting the input supply voltage to the lowest operating input voltage 2.75V and set the input supply's current limit to zero. With the input supply off connect up the input supply to Vin and GND. Connect a digital volt meter and a load if needed to set the minimum lout of the design from Vout and GND. Turn on the input supply and slowly turn up the current limit on the input supply. If the voltage starts to rise on the input supply continue increasing the input supply current limit while watching the output voltage. If the current increases on the input supply, but the voltage remains near zero, then there may be a short or a component misplaced on the board. Power down the board and visually inspect for solder bridges and recheck the diode and capacitor polarities. Once the power supply circuit is operational then more extensive testing may include full load testing, transient load and line tests to compare with simulation results.

Load Testing

The setup is the same as the initial startup, except that an additional digital voltmeter is connected between Vin and GND, a load is connected between Vout and GND and a current meter is connected in series between Vout and the load. The load must be able to handle at least rated output power + 50% (7.5 watts for this design). Ideally the load is supplied in the form of a variable load test unit. It can also be done in the form of suitably large power resistors. When using an oscilloscope to measure waveforms on the prototype board, the ground leads of the oscilloscope probes should be as short as possible and the area of the loop formed by the ground lead should be kept to a minimum. This will help reduce ground lead inductance and eliminate EMI noise that is not actually present in the circuit.

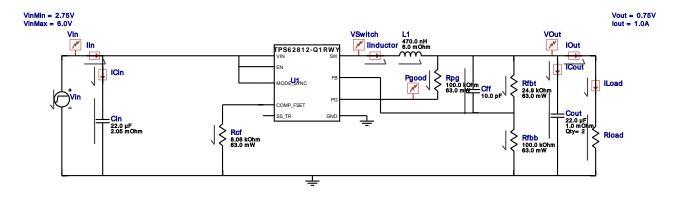


WEBENCH[®] Electrical Simulation Report

Design Id = 168

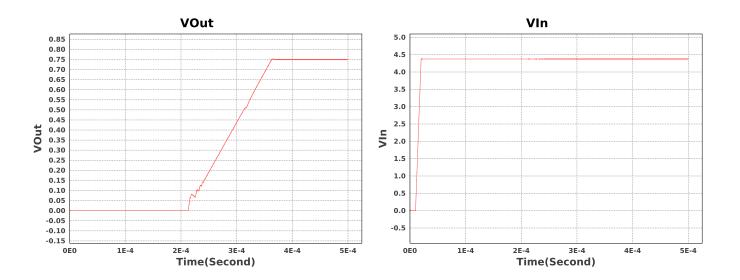
 $sim_id = 1$

Simulation Type = Startup



Simulation Parameters

#	Name	Parameter Name	Description	Values
1.	Rload	R	Load Resistance	0.75 Ohm



Design Assistance

- 1. The TPS62812-Q1 is qualified for Automotive applications. All passives and other components selected in this design may not be qualified for Automotive applications. The user is required to verify that all components in the design meet the qualification and safety requirements for their specific application
- 2. Master key: 4787750D4FBA71E4[v1]
- 3. TPS62812-Q1 Product Folder: http://www.ti.com/product/TPS62812%2DQ1: contains the data sheet and other resources.

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